

WHAT IS CLAIMED IS:

1. A conductive paste adapted to be sintered with a ceramic body at the same time, the conductive paste comprising a conductive component and an organic vehicle,
wherein the conductive component comprises a copper powder
5 coated with a first metal oxide having a melting point exceeding the melting point of copper and a
powder of a second metal oxide having a melting point exceeding the melting point of the copper;
the content of the first metal oxide is in the range of about 0.05% by
10 weight to about 5% by weight of the total weight of the coated copper powder and the metal oxide powder; and
the total content of the first metal oxide and the powder of the second metal oxide is in the range of about 1% by weight to about 12 % by weight of the total weight of the coated copper powder and the metal oxide powder.
2. The conductive paste according to claim 1, wherein the first metal oxide comprises at least one metal oxide selected from the group consisting of Al_2O_3 , ZrO_2 , TiO_2 , SiO_2 , Nb_2O_5 and Ta_2O_5 .
3. The conductive paste according to claim 2, wherein the second metal oxide comprises at least one metal oxide selected from the group consisting of Al_2O_3 , ZrO_2 , TiO_2 , SiO_2 , Nb_2O_5 and Ta_2O_5 .
4. The conductive paste according to claim 3, wherein the first metal oxide is Al_2O_3 .
5. The conductive paste according to claim 4, wherein the second metal oxide is Al_2O_3 .
6. The conductive paste according to claim 5, wherein the viscosity of the paste is about 10 to 700 Pa·s.

7. The conductive paste according to claim 1, wherein the first metal oxide is Al_2O_3 .
8. The conductive paste according to claim 1, wherein the second metal oxide is Al_2O_3 .
9. The conductive paste according to claim 1, wherein the viscosity of the paste is about 10 to 700 Pa·s.
10. The conductive paste according to claim 8, wherein the vehicle is about 10-55 weight percent thereof.
11. A ceramic multilayer substrate comprising a ceramic sinter and a conductive sinter, wherein the conductive sinter is a sintered conductive paste according to claim 10.
12. A ceramic multilayer substrate comprising a ceramic sinter and a conductive sinter, wherein the conductive sinter is a sintered conductive paste according to claim 9.
13. A ceramic multilayer substrate comprising a ceramic sinter and a conductive sinter, wherein the conductive sinter is a sintered conductive paste according to claim 8.
14. A ceramic multilayer substrate comprising a ceramic sinter and a conductive sinter, wherein the conductive sinter is a sintered conductive paste according to claim 7.
15. A ceramic multilayer substrate comprising a ceramic sinter and a conductive sinter, wherein the conductive sinter is a sintered conductive paste according to claim 6.
16. A ceramic multilayer substrate comprising a ceramic sinter and a conductive sinter, wherein the conductive sinter is a sintered conductive paste according to claim 5.

17. A ceramic multilayer substrate comprising a ceramic sinter and a conductive sinter, wherein the conductive sinter is a sintered conductive paste according to claim 4.

18. A ceramic multilayer substrate comprising a ceramic sinter and a conductive sinter, wherein the conductive sinter is a sintered conductive paste according to claim 3.

19. A ceramic multilayer substrate comprising a ceramic sinter and a conductive sinter, wherein the conductive sinter is a sintered conductive paste according to claim 2.

20. A ceramic multilayer substrate comprising a ceramic sinter and a conductive sinter, wherein the conductive sinter is a sintered conductive paste according to claim 1.